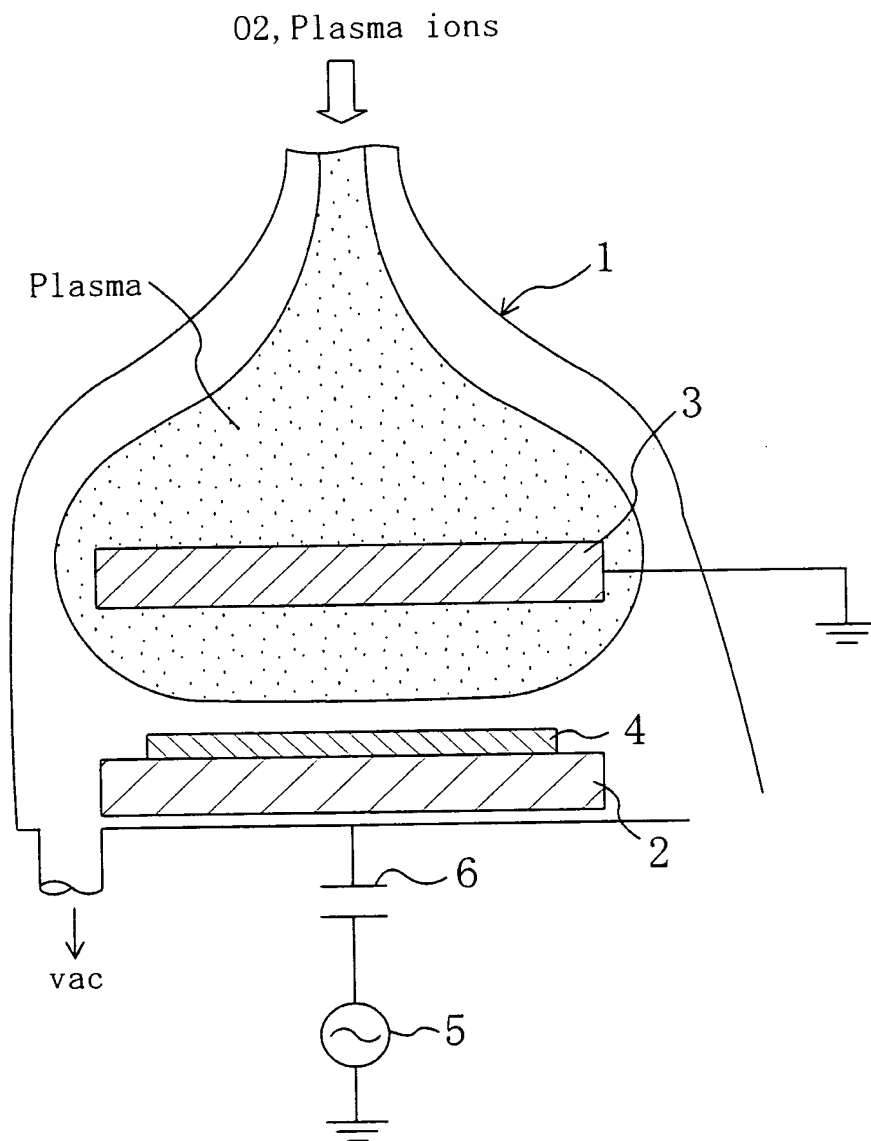


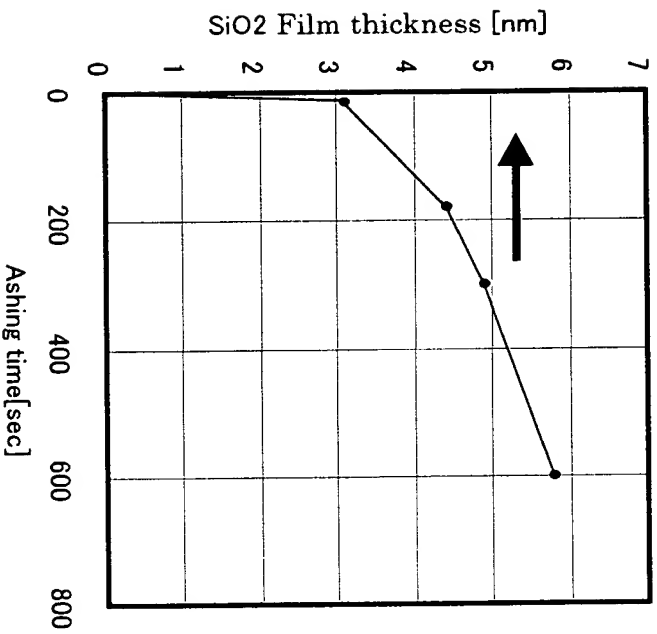
Fig. 1



004760 40029960

Fig.2(a)

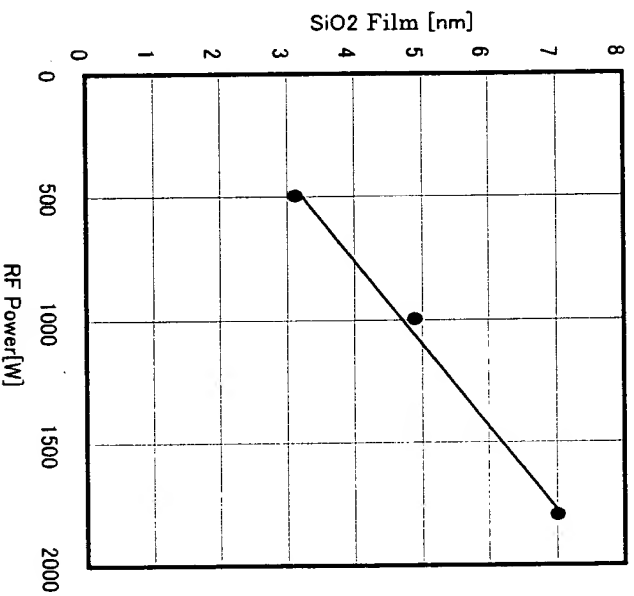
Dependency of film thickness on plasma time



High frequency power [W]	1000
Pressure [pa]	66
Oxygen flow rate [ml/min]	800
Temperature [°C]	180
Time [sec]	Y

Fig.2(b)

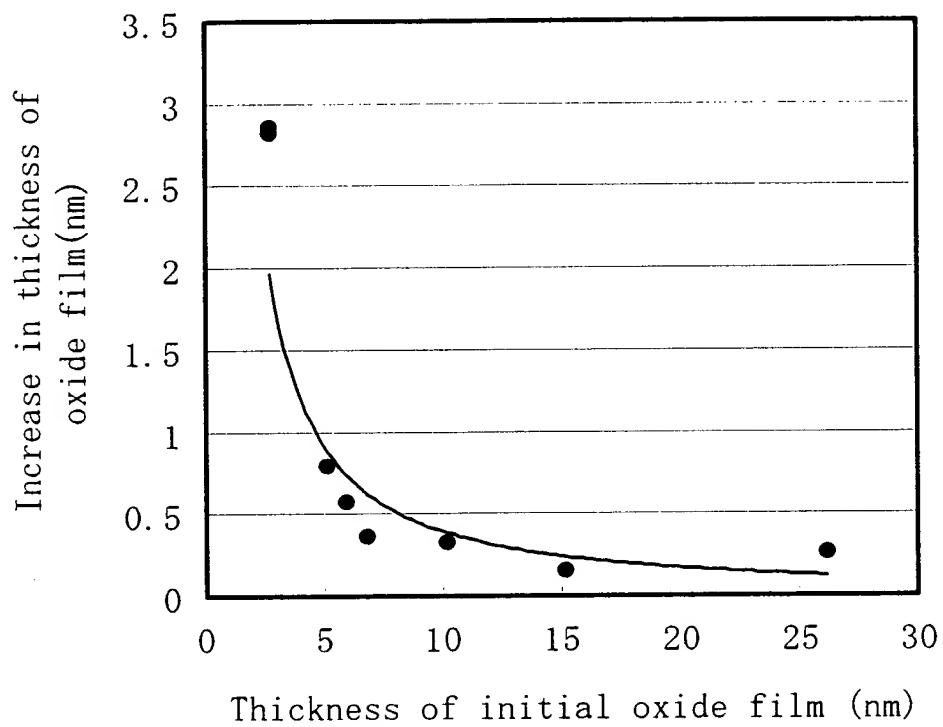
Dependency of film thickness on bias



Conditions				
O2	800[ml/min]	800[ml/min]	800[ml/min]	
RF Power	66[Pa]	66[Pa]	66[Pa]	
Temp	500[W]	1000[W]	1800[W]	
Time	180[°C]	180[°C]	180[°C]	
	5[min]	5[min]	5[min]	

001760"40029960

Fig. 3



004T60" 40029960

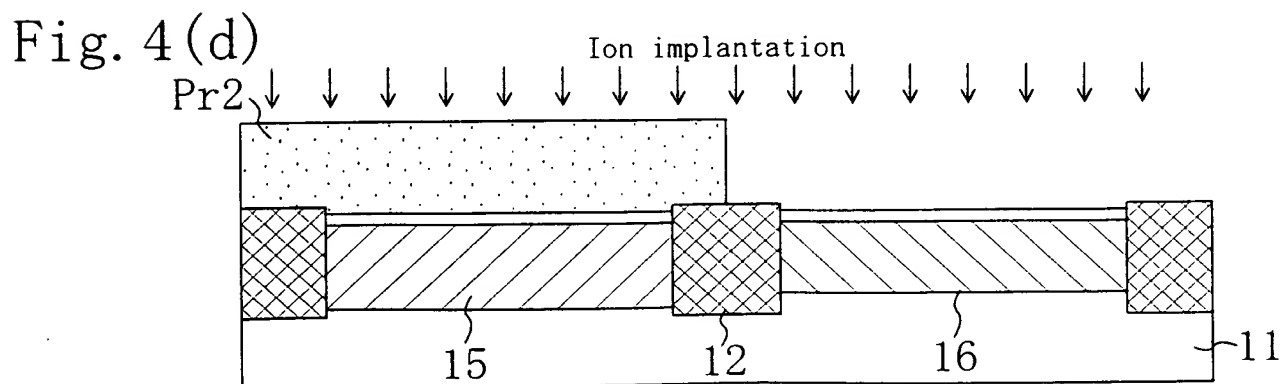
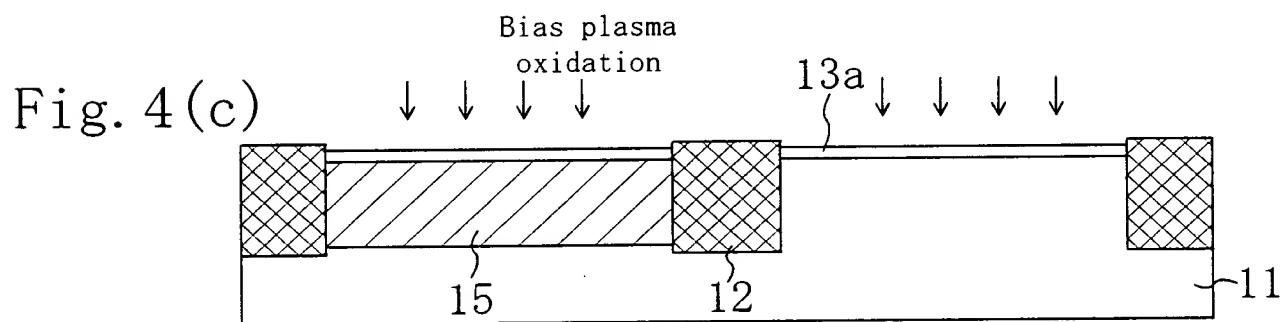
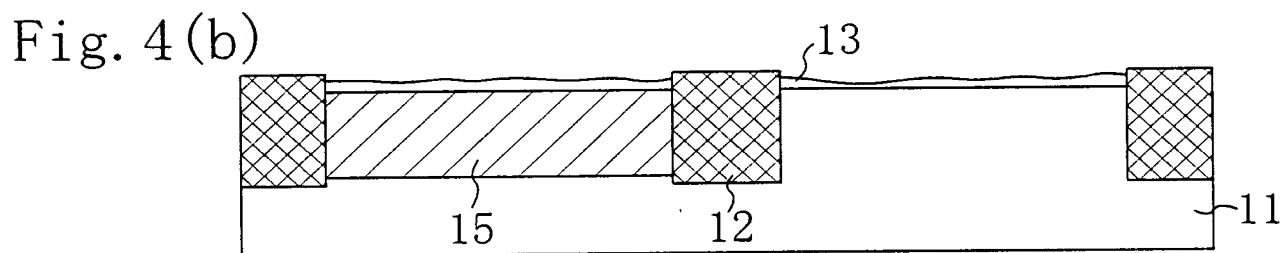
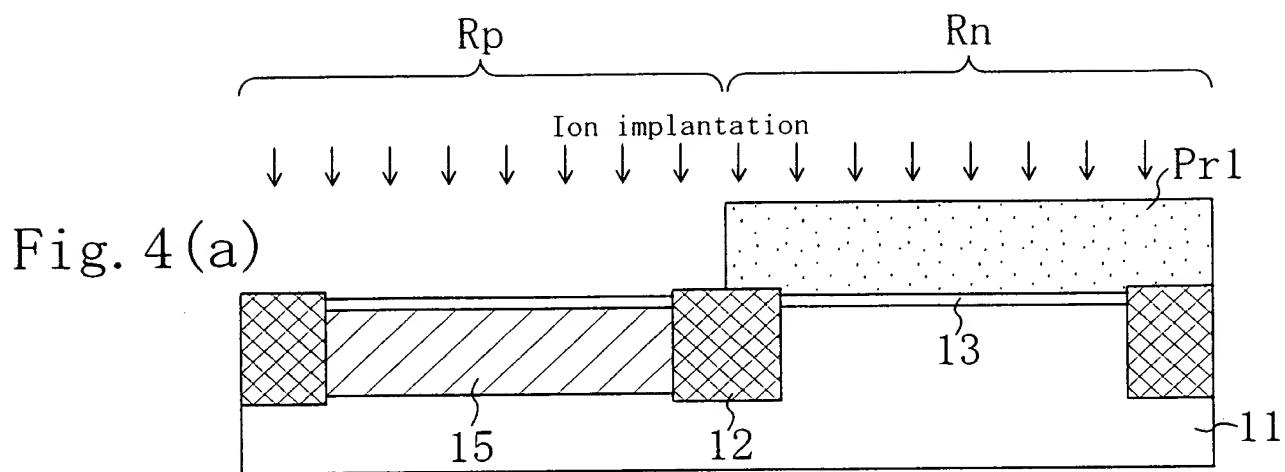


Fig. 5 (a)

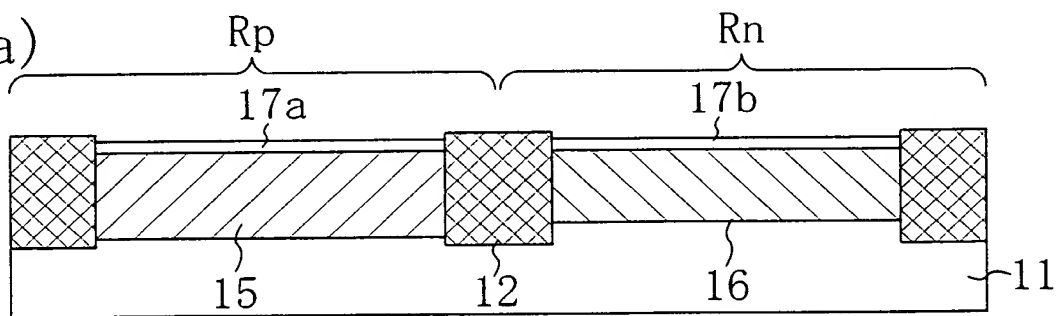


Fig. 5 (b)

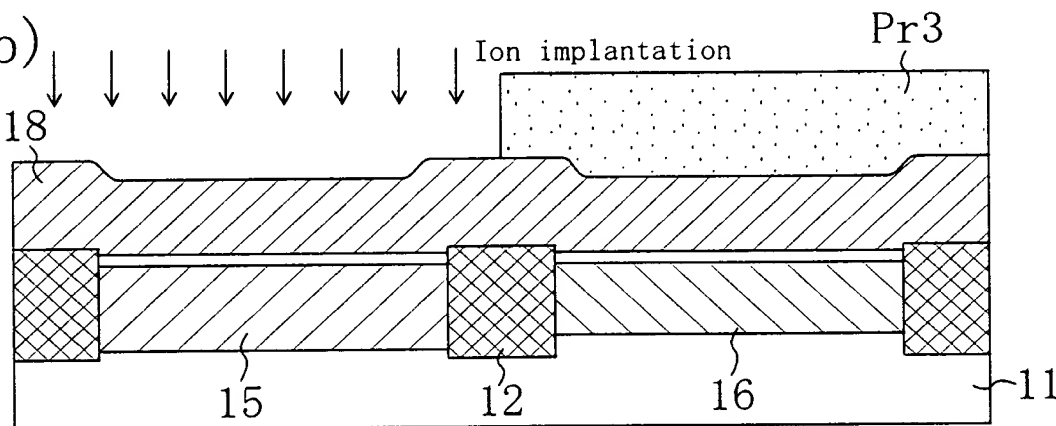


Fig. 5 (c)

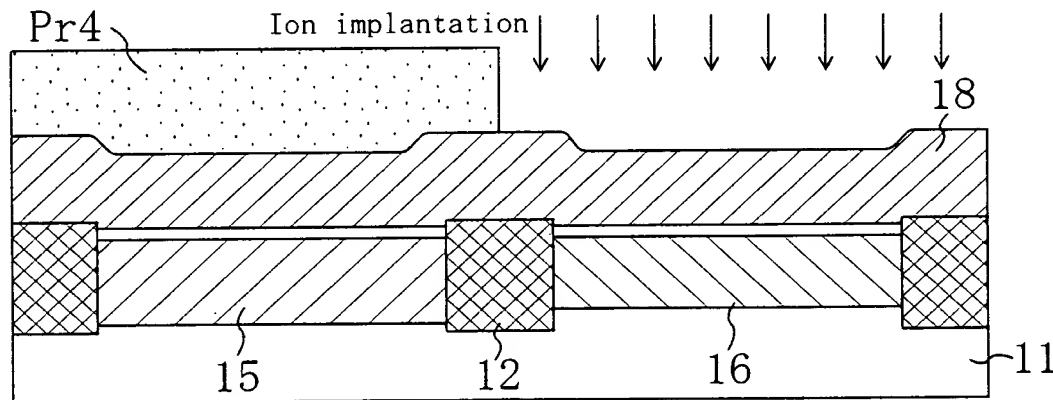
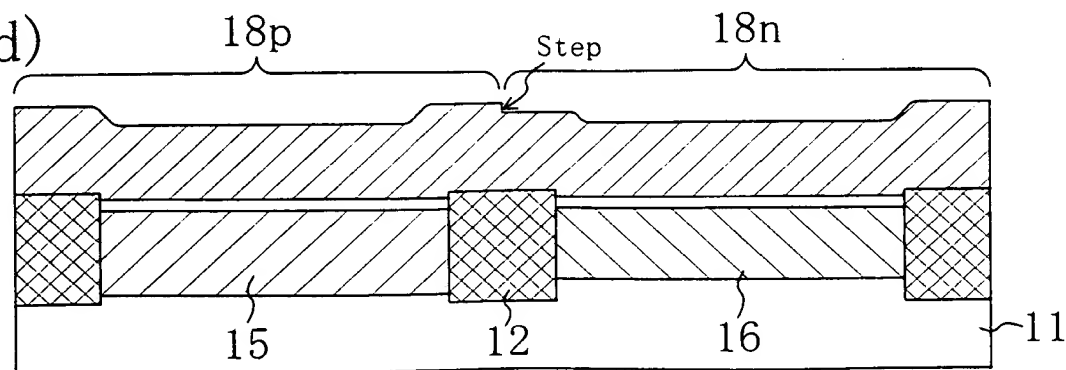


Fig. 5 (d)



004760" 40029960

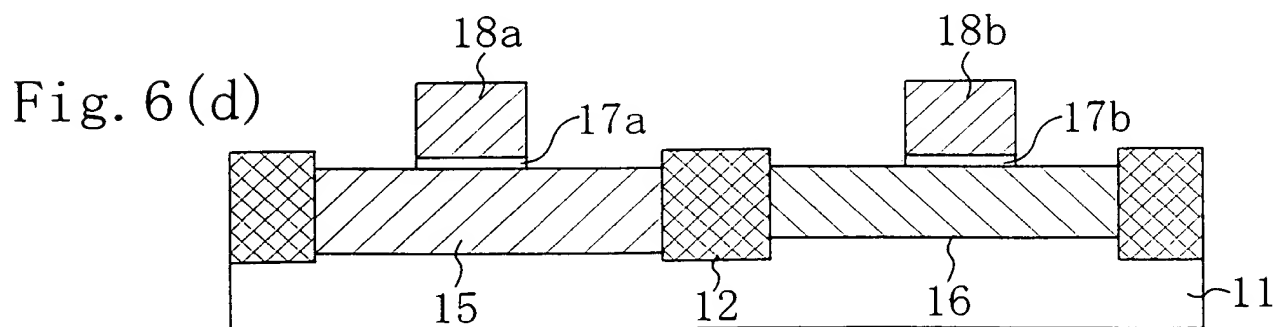
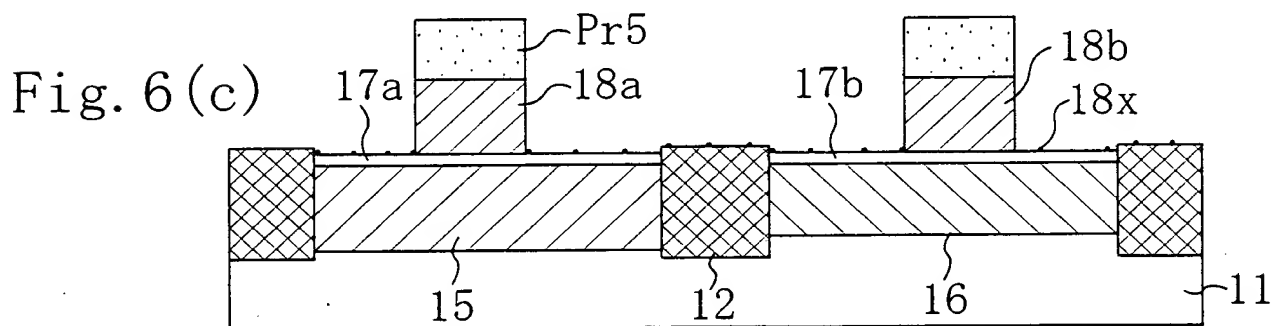
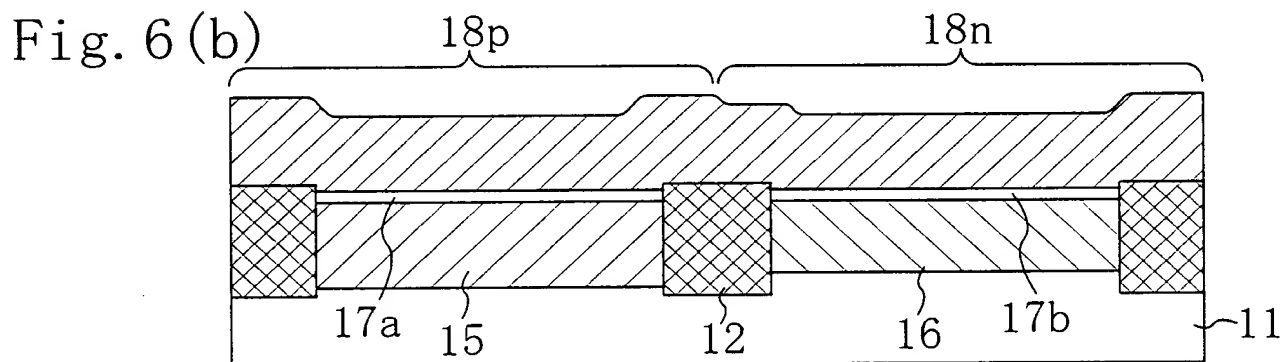
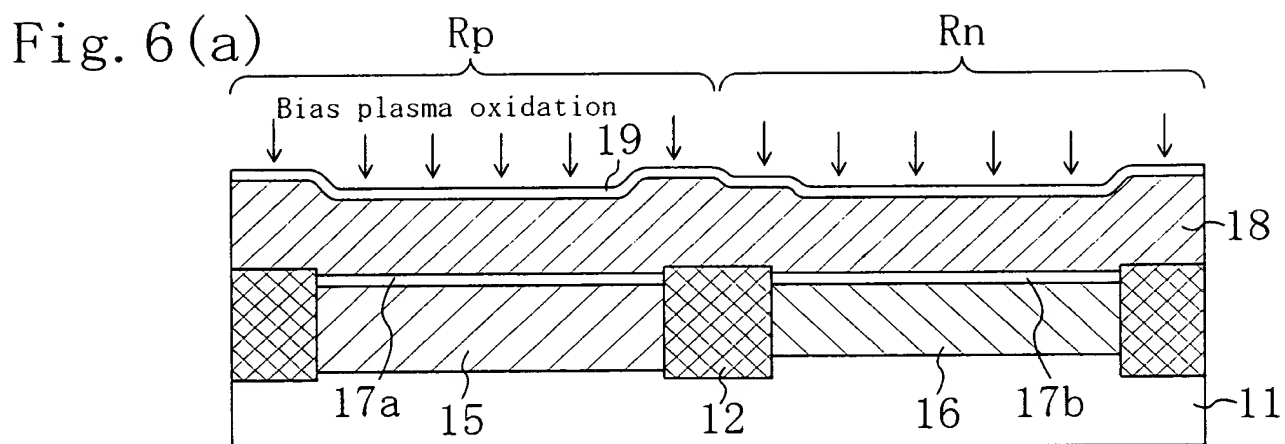


Fig. 7(a)

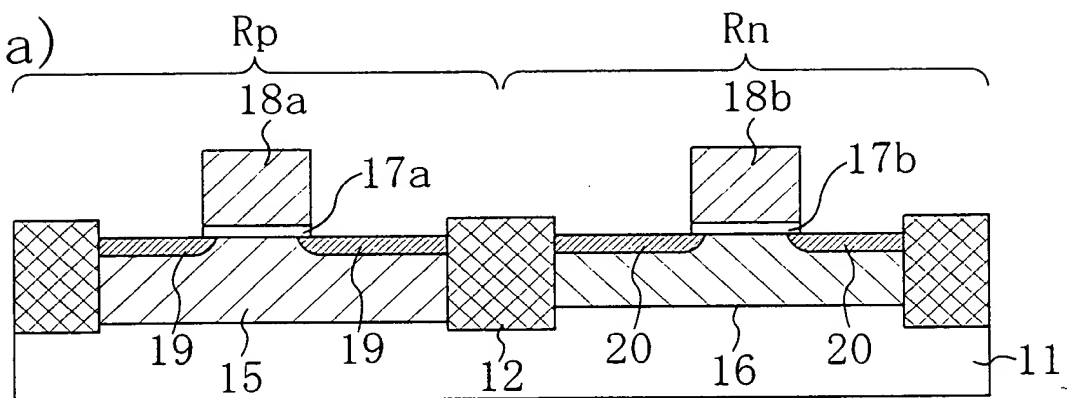


Fig. 7(b)

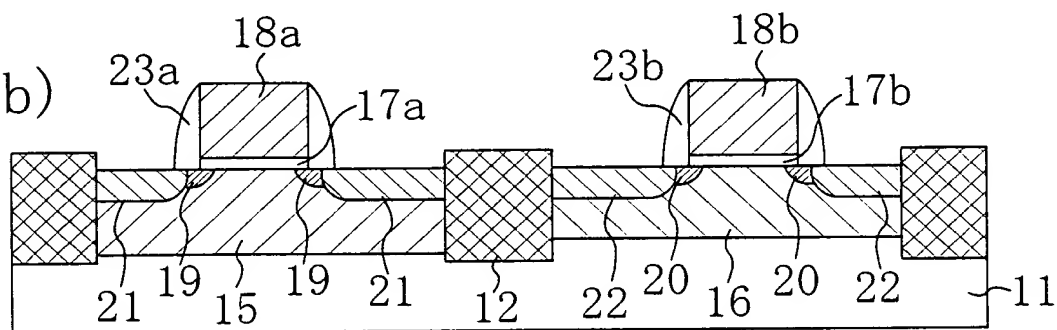


Fig. 7(c)

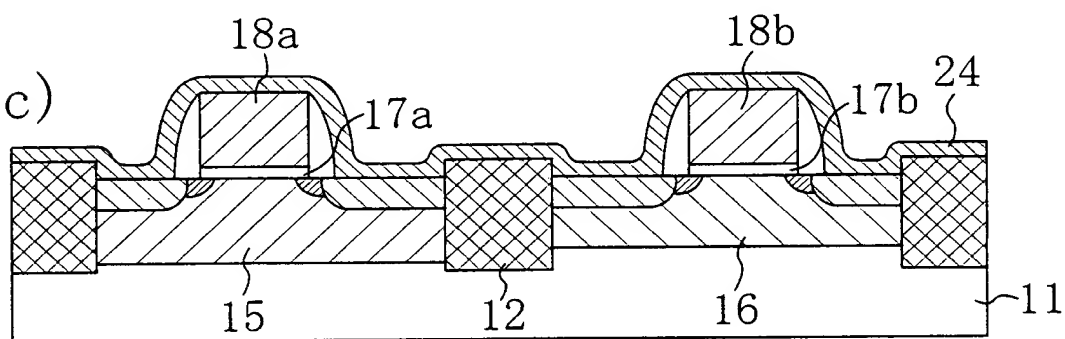
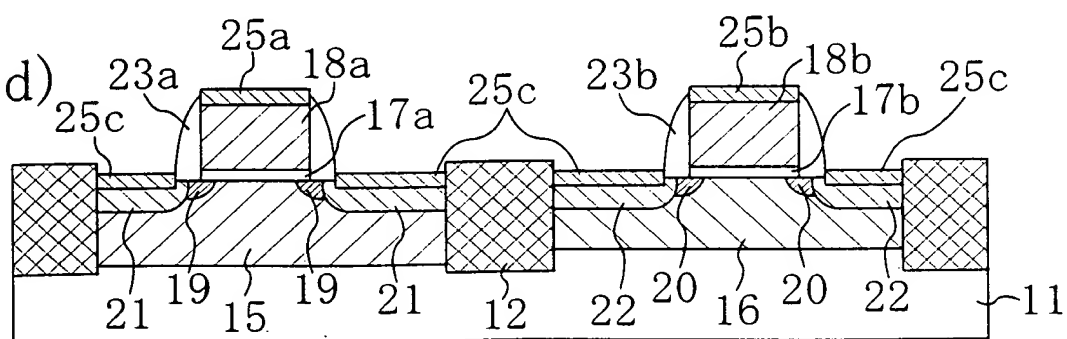


Fig. 7(d)



66pa/800mtorr/180°C/3min

Fig. 8(c)

sl.23 (No implantation)

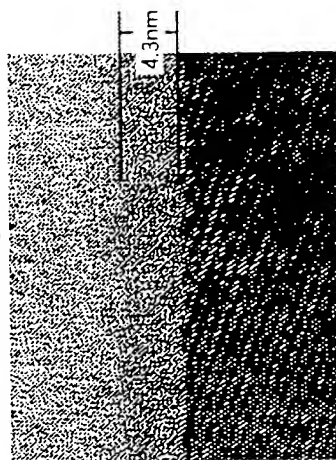


Fig. 8(b)

sl.22 (Pch)

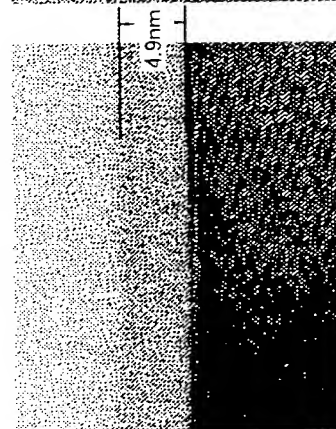
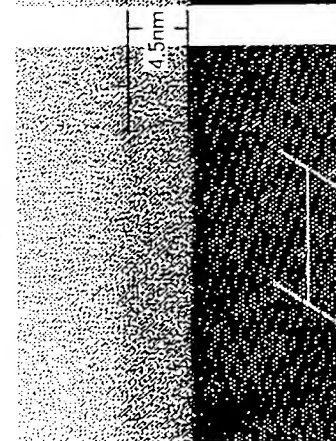
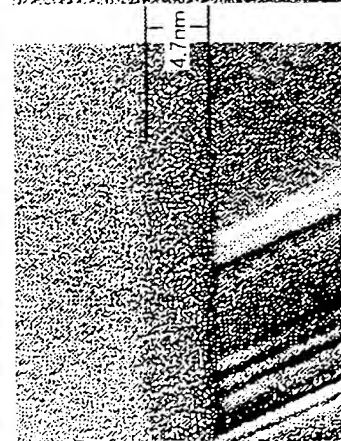
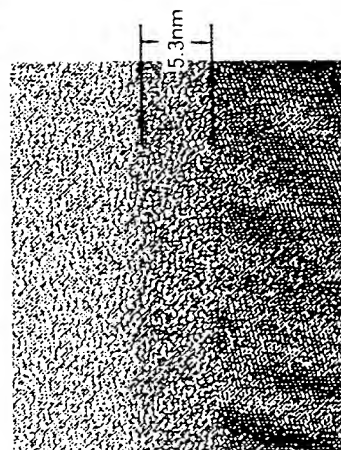


Fig. 8(a)

sl.21 (Nch)



On Si substrate



On polysilicon

10nm

Fig. 8(e)

Fig. 8(d)

Fig. 9

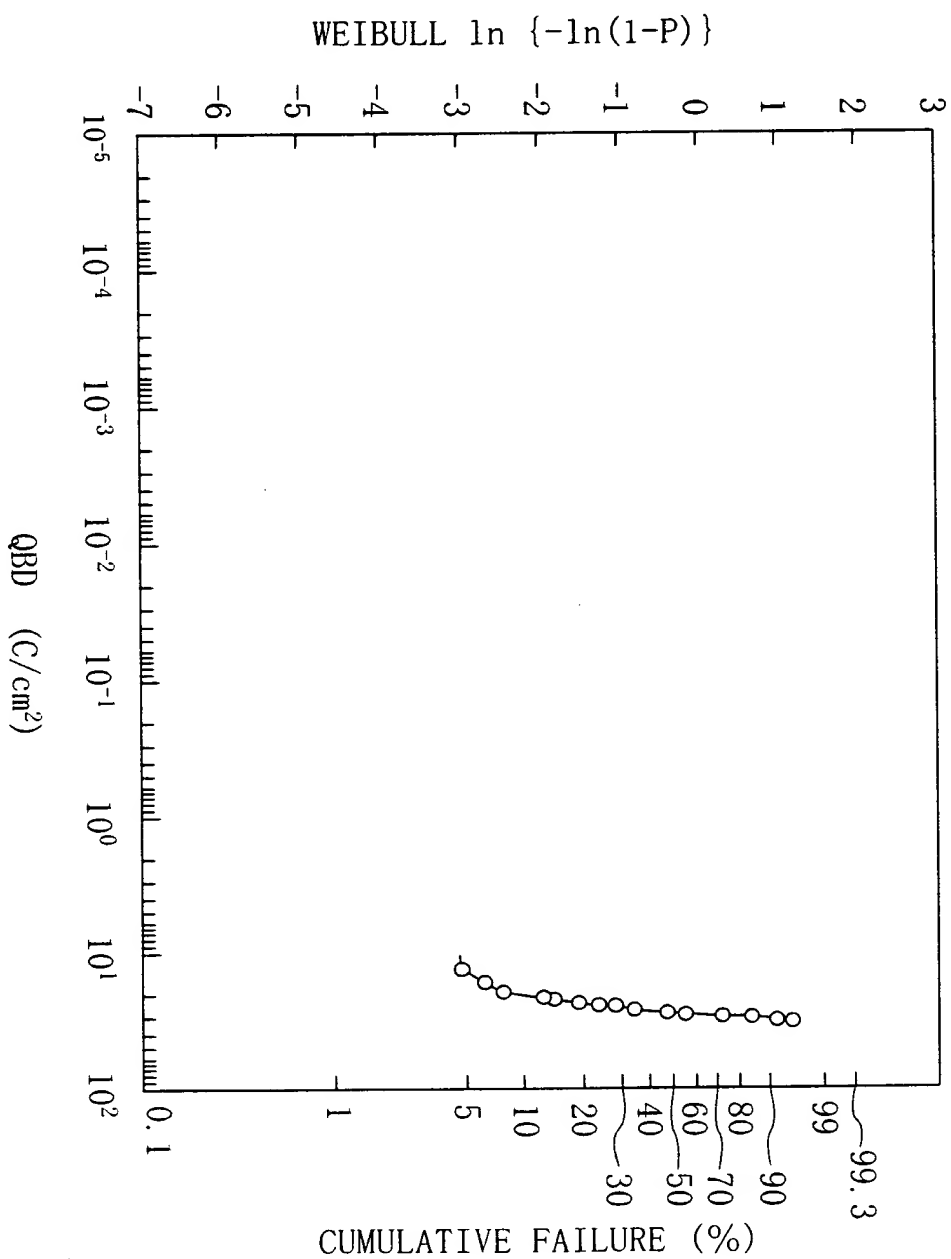
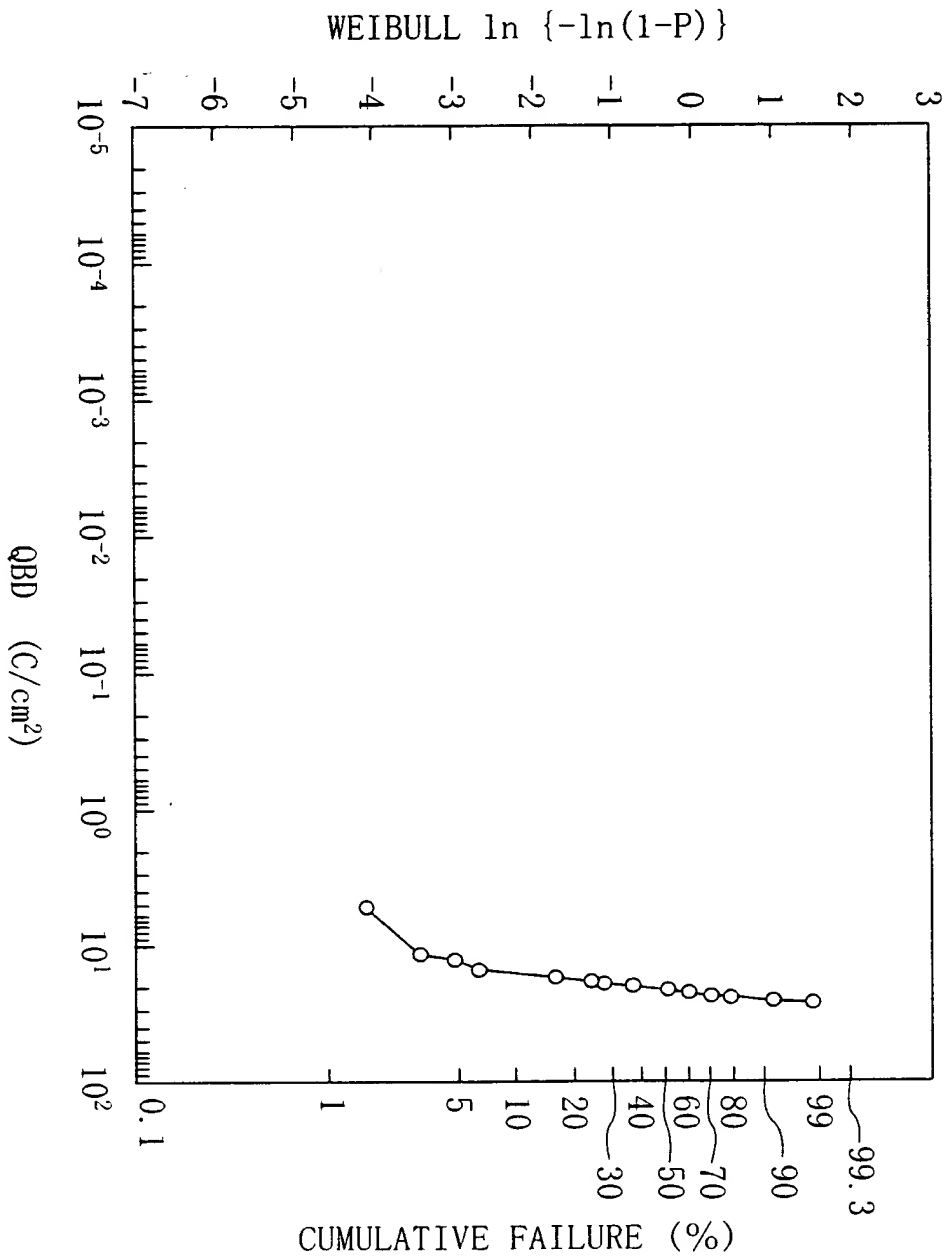


Fig. 10



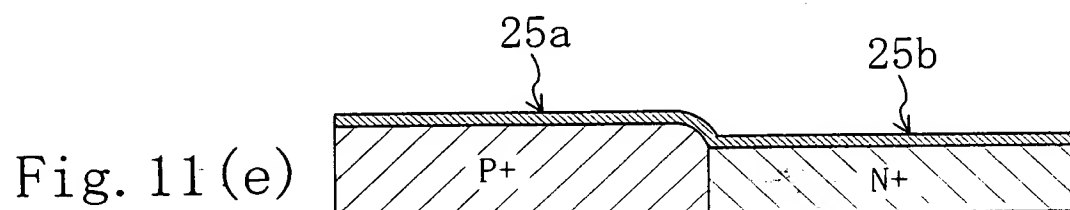
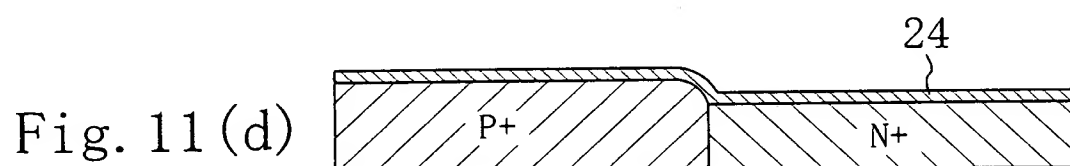
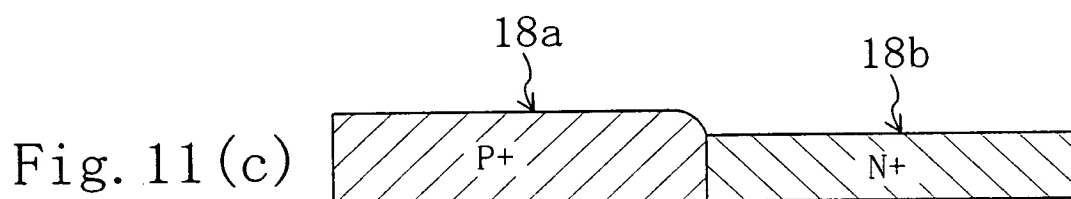
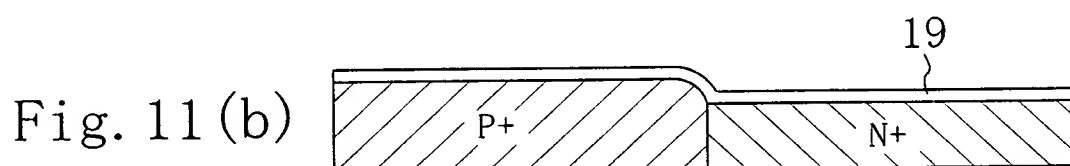
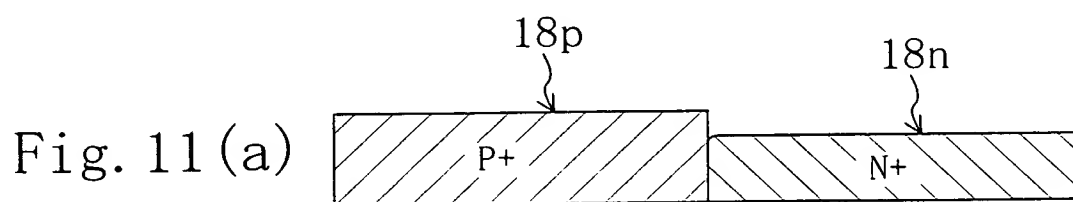
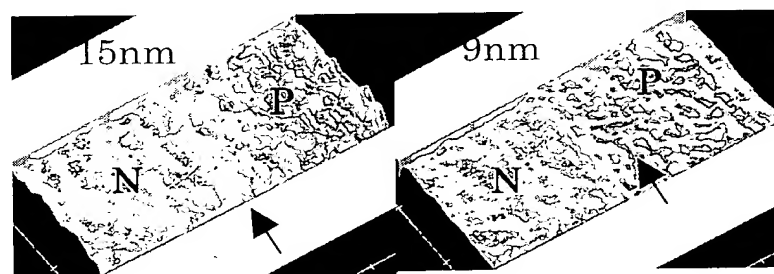


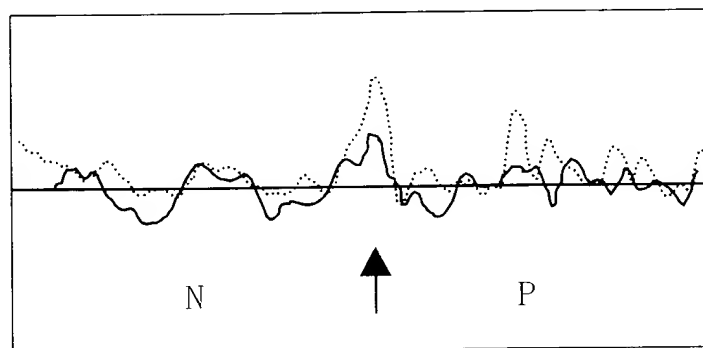
Fig. 12(a)

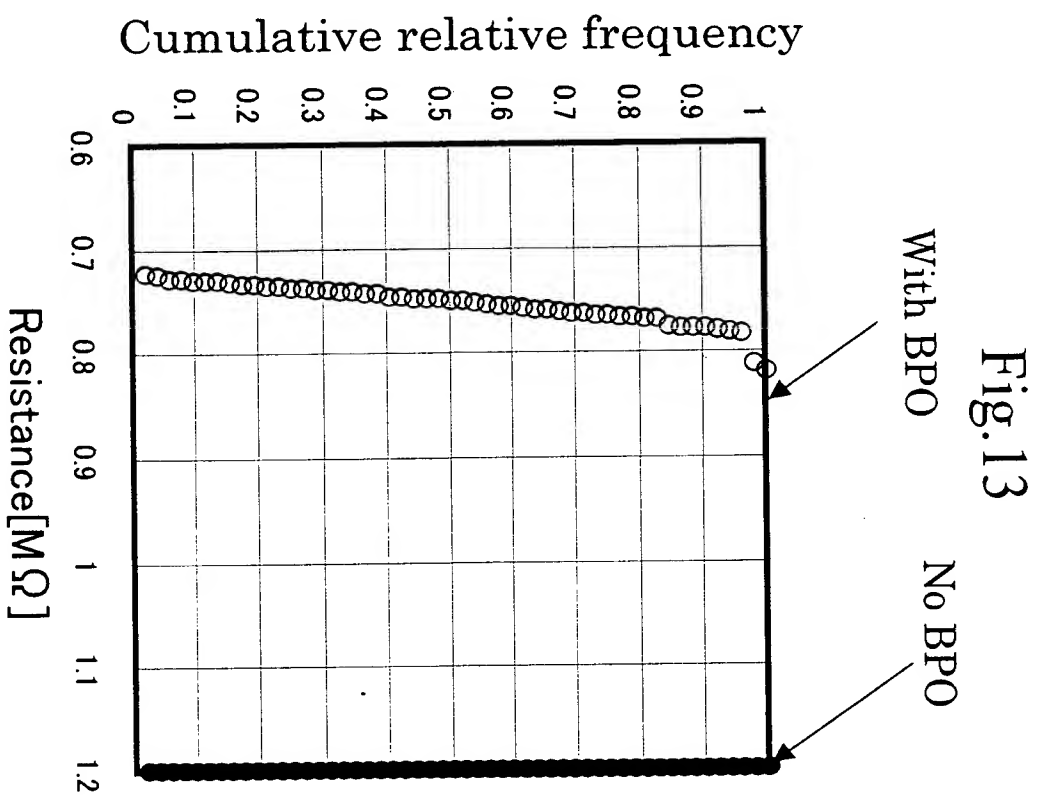


(1) No plasma oxidation (2) With plasma oxidation

Fig. 12(b)

—— With BPO
 No BPO





004760 40029960

Fig. 14(a)

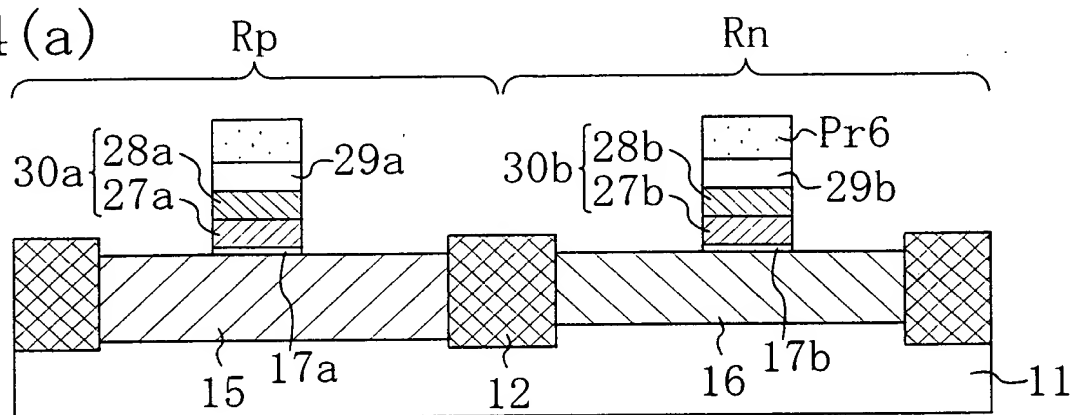


Fig. 14(b)

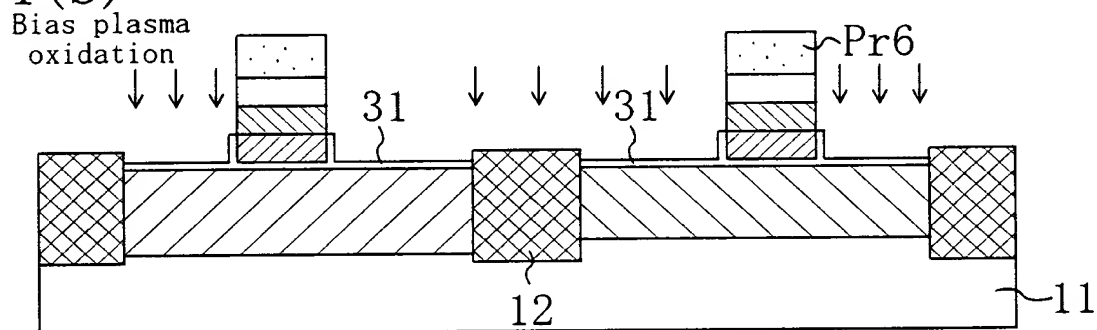


Fig. 14(c)

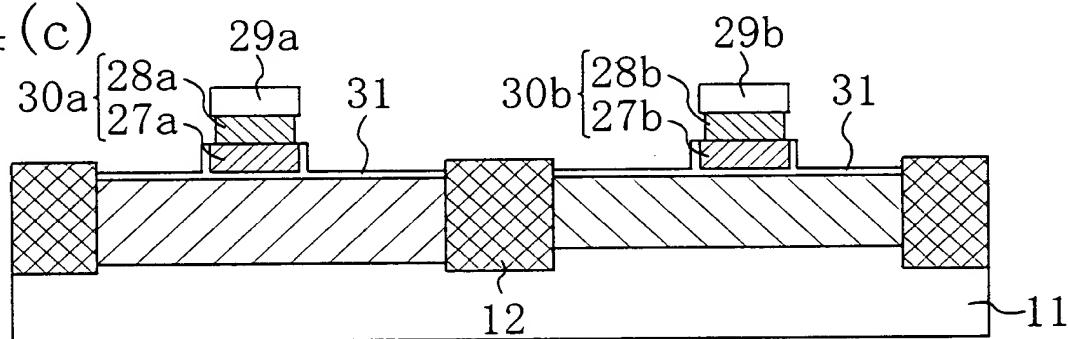
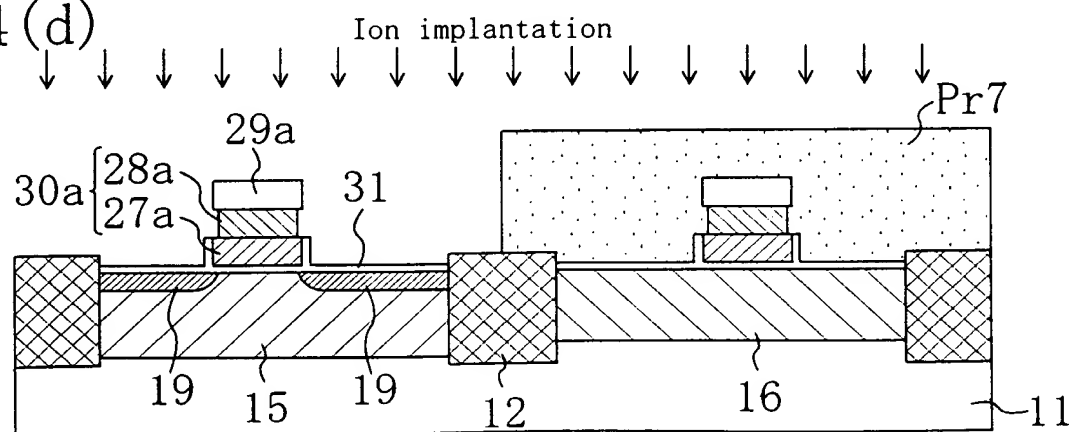


Fig. 14(d)



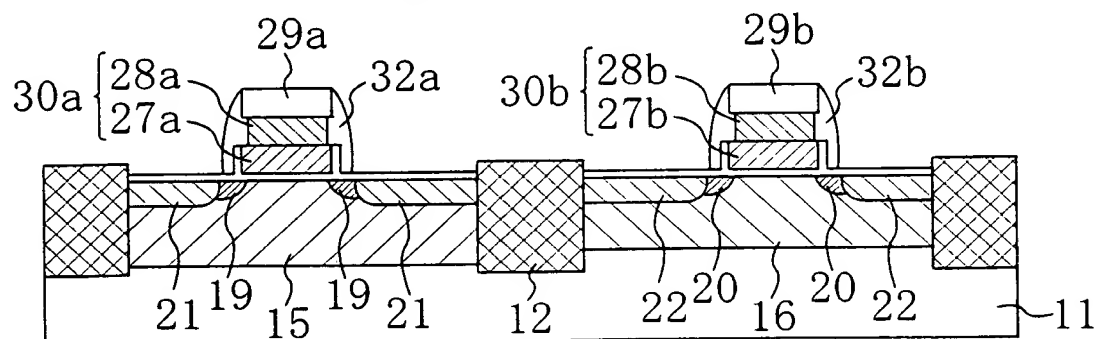
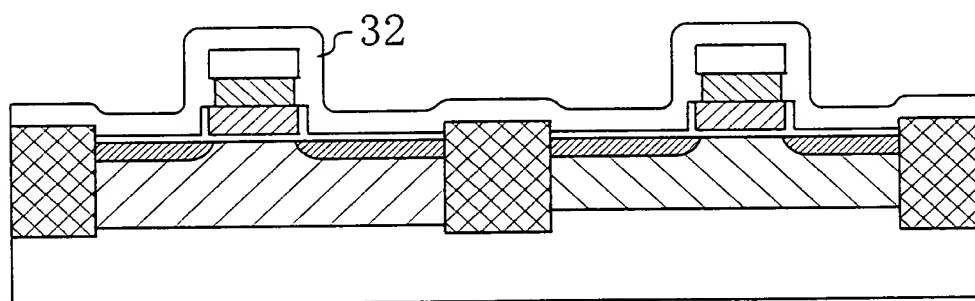
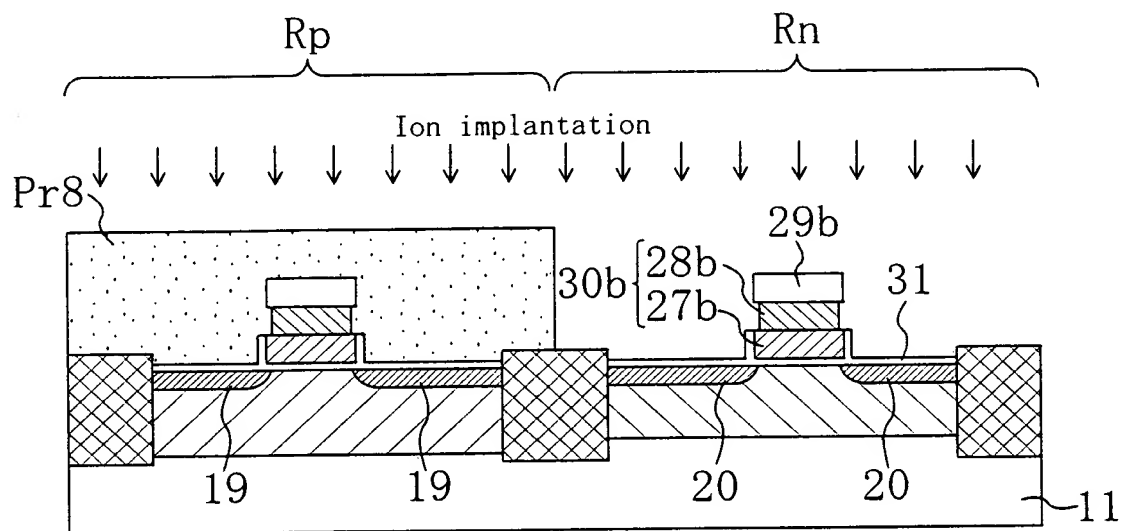


Fig. 16

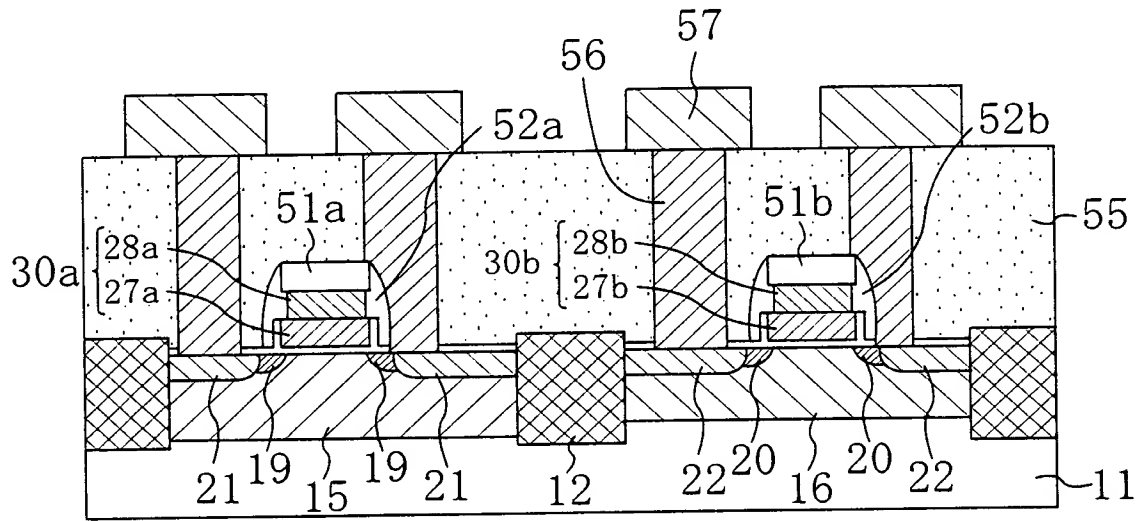


Fig. 17(a)

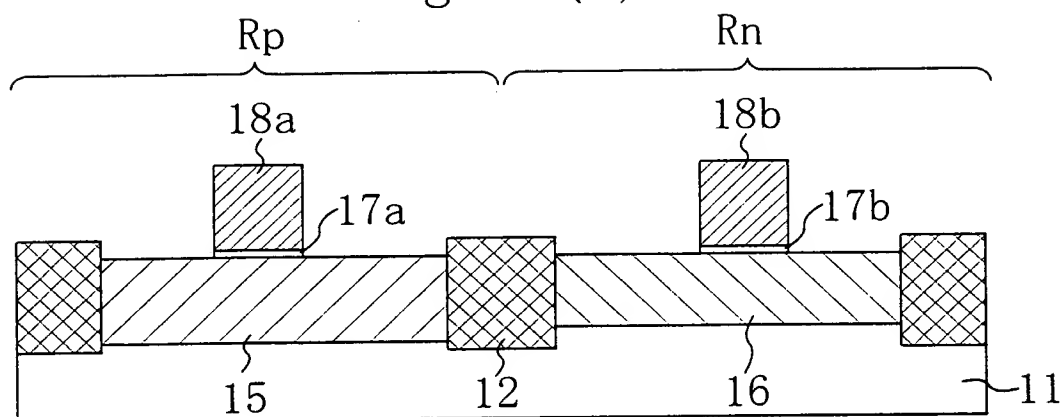


Fig. 17(b)

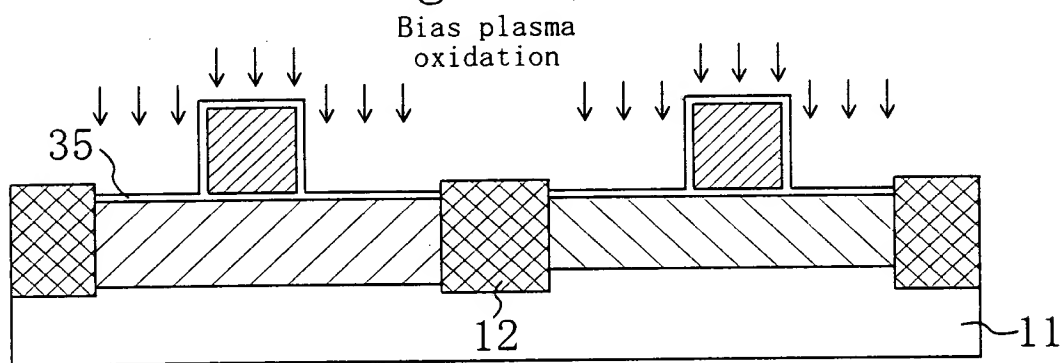


Fig. 17(c)

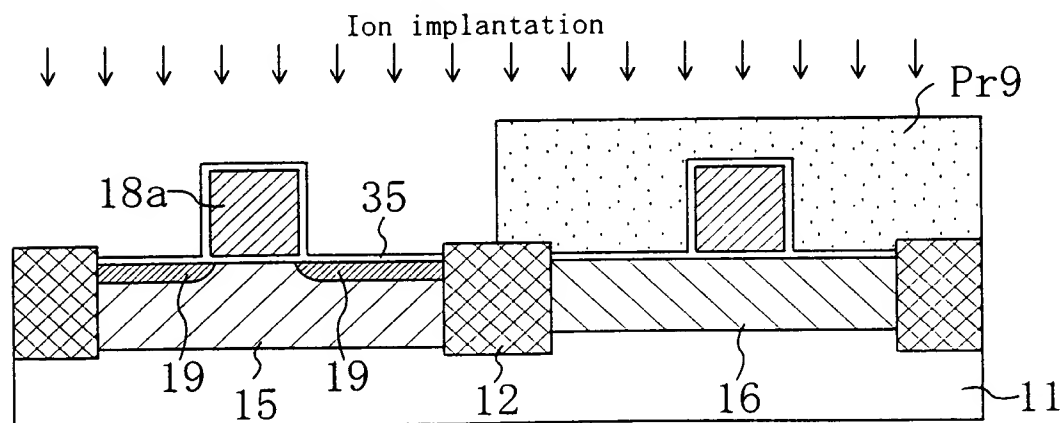


Fig. 18(a)

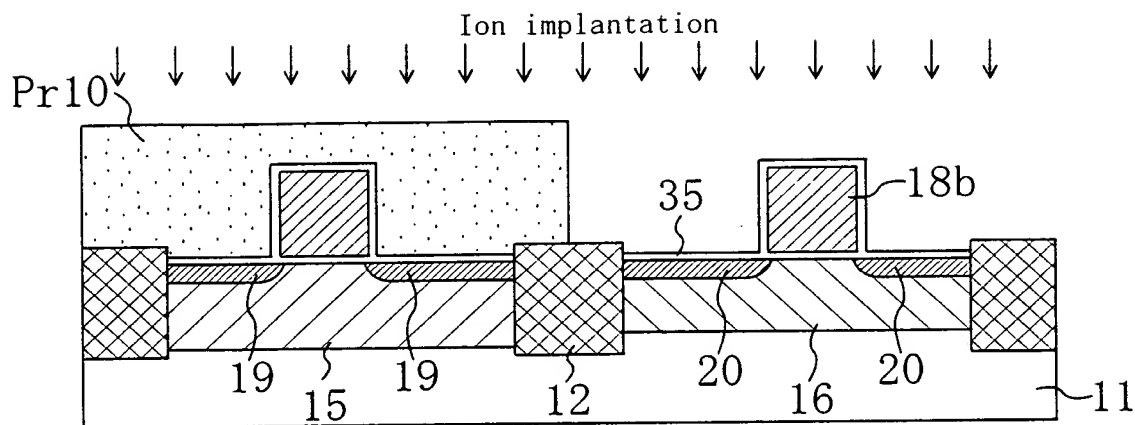


Fig. 18(b)

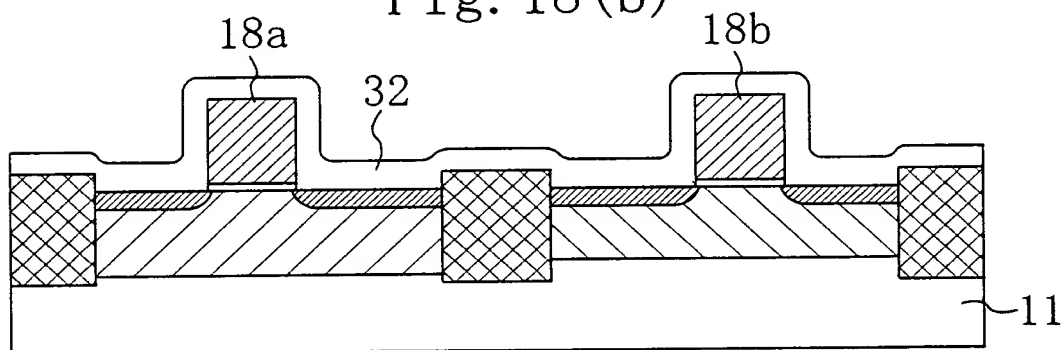


Fig. 18(c)

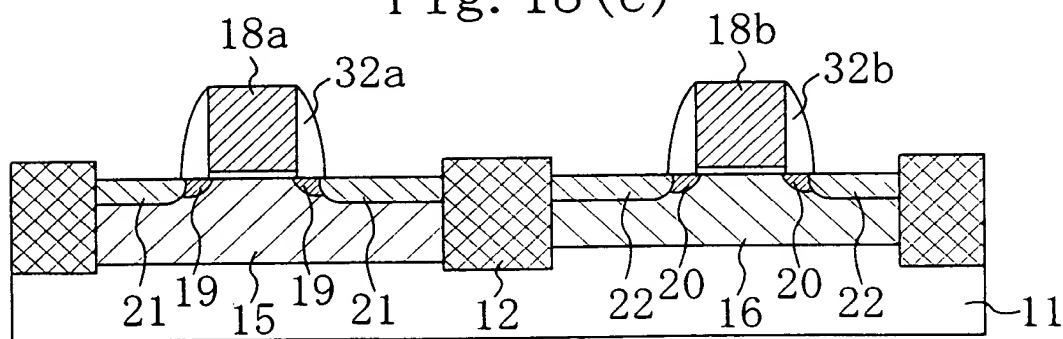


Fig.19(a)

Pch Transistor

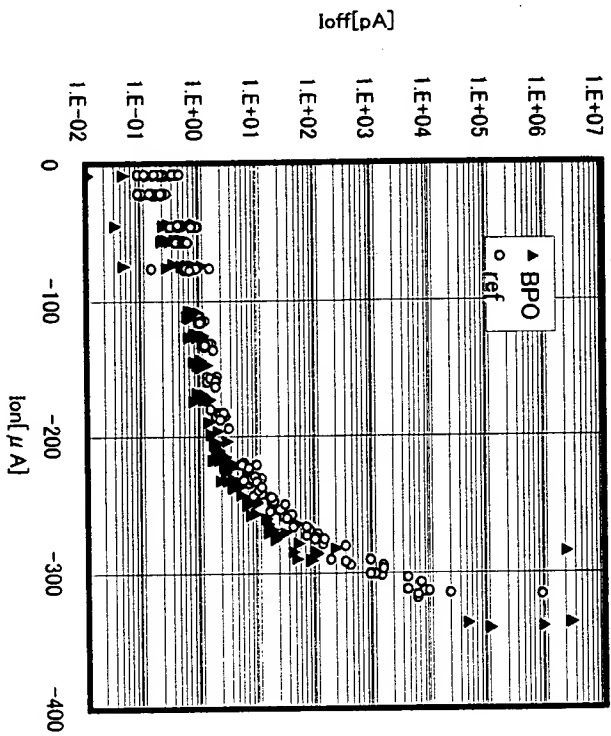
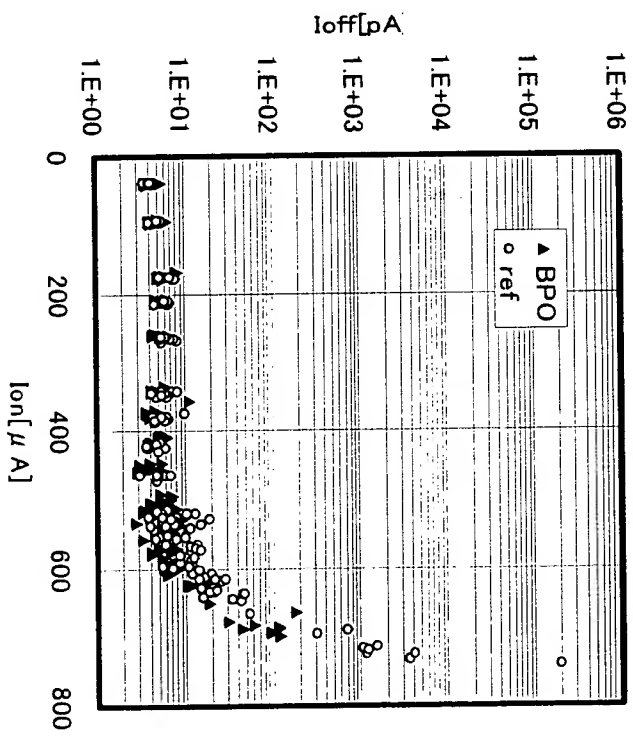


Fig.19(b)

Nch Transistor



004160" 40029960

Fig. 20(a)

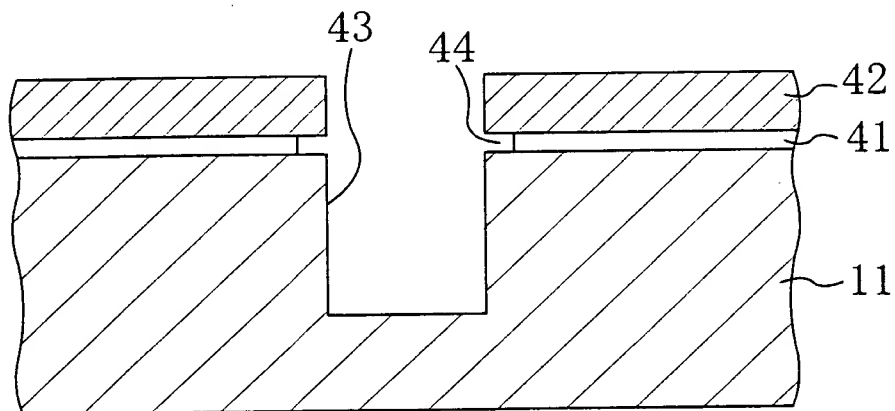


Fig. 20(b)

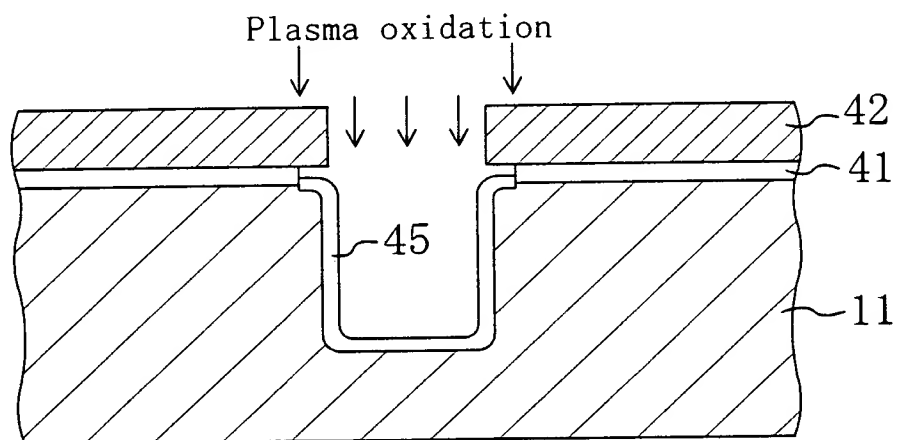


Fig. 20(c)

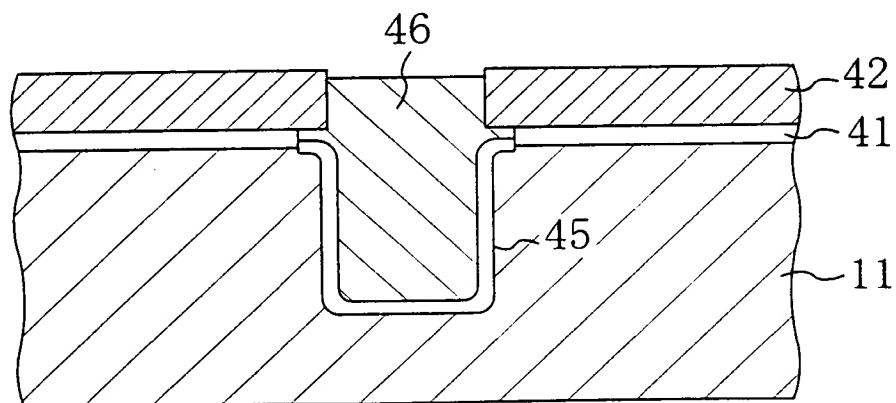


Fig. 21 (a)

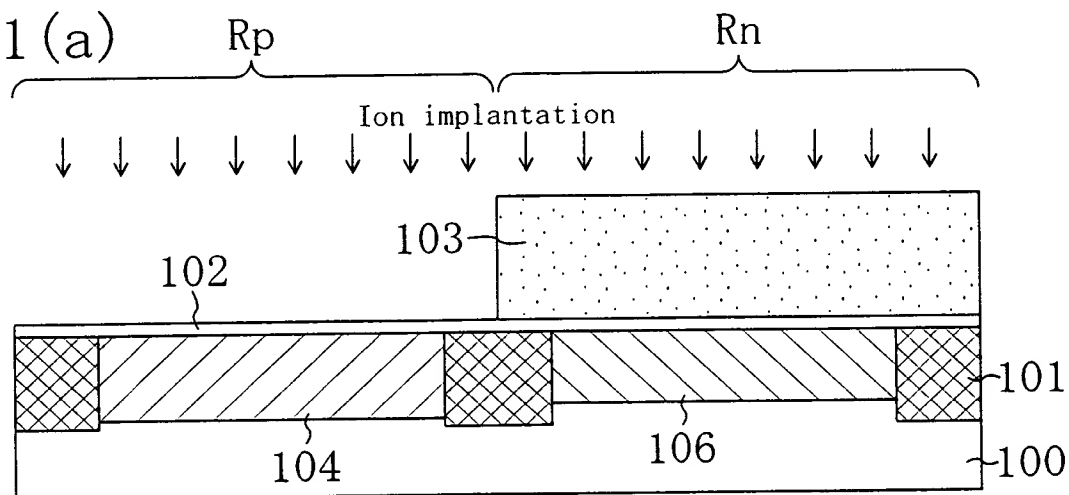


Fig. 21 (b)

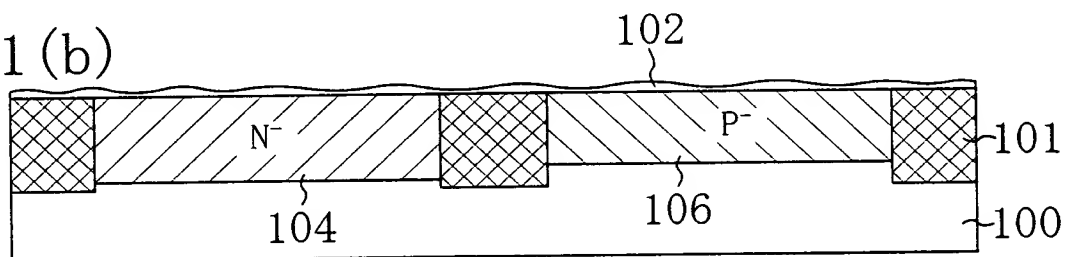


Fig. 21 (c)

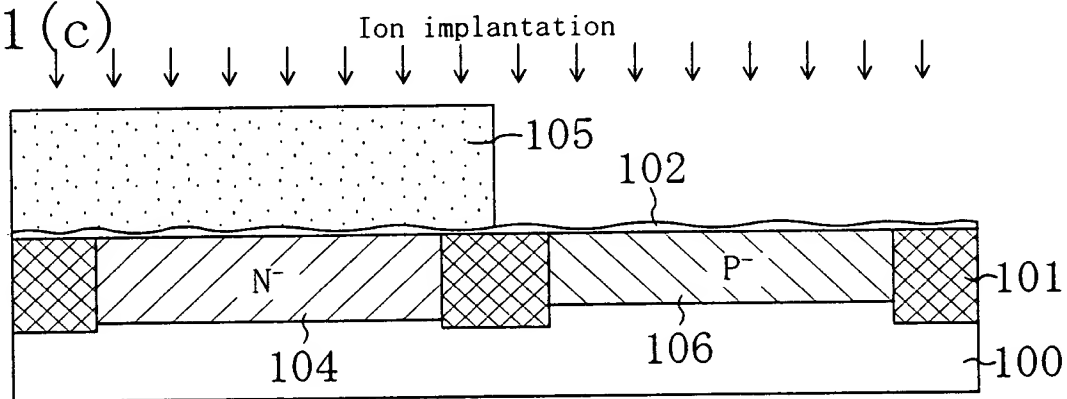


Fig. 21 (d)

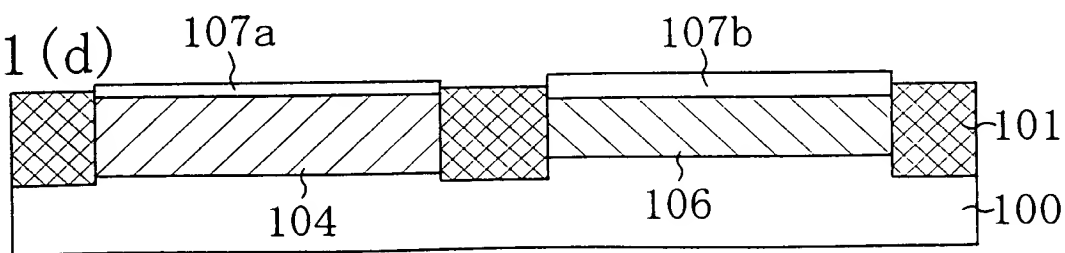


Fig. 22(a)

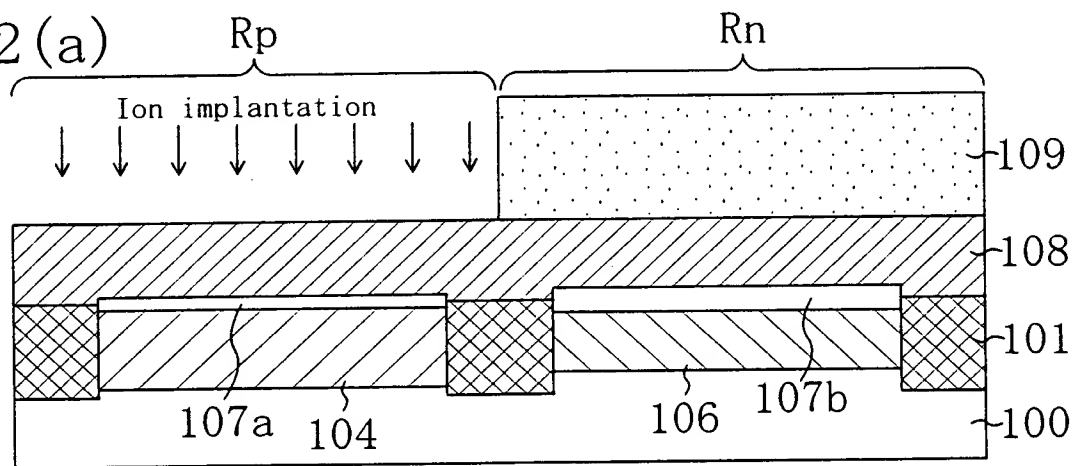


Fig. 22(b)

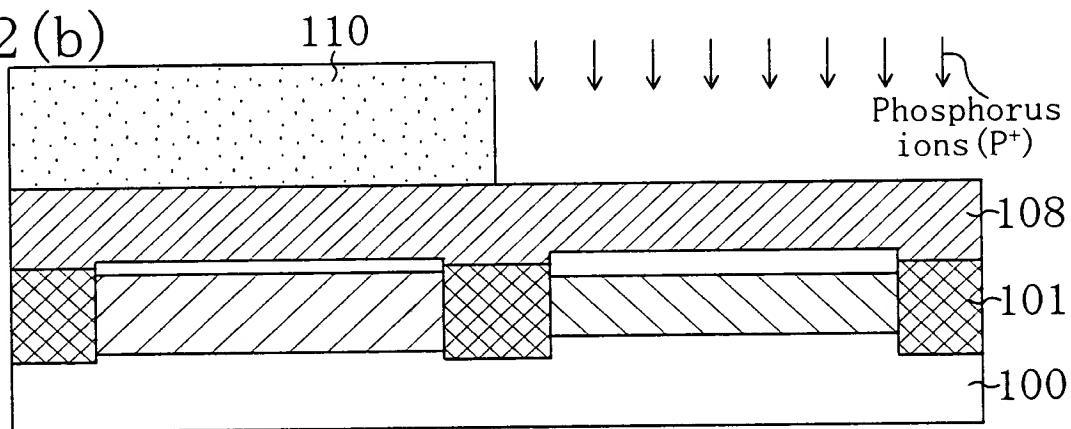


Fig. 22(c)

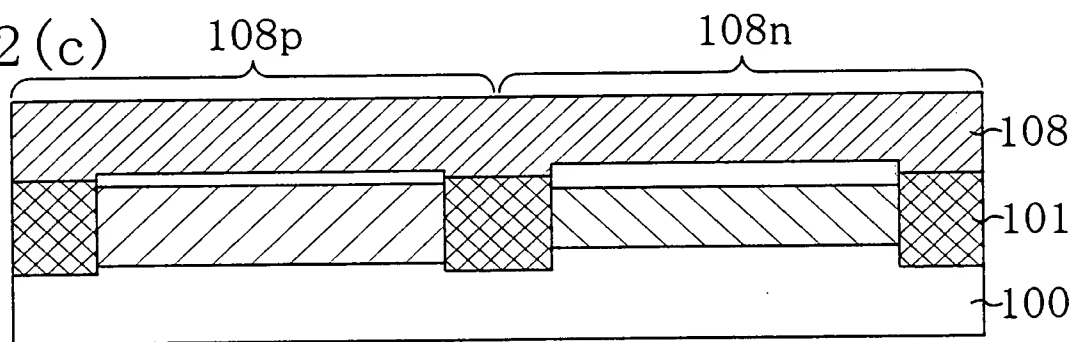
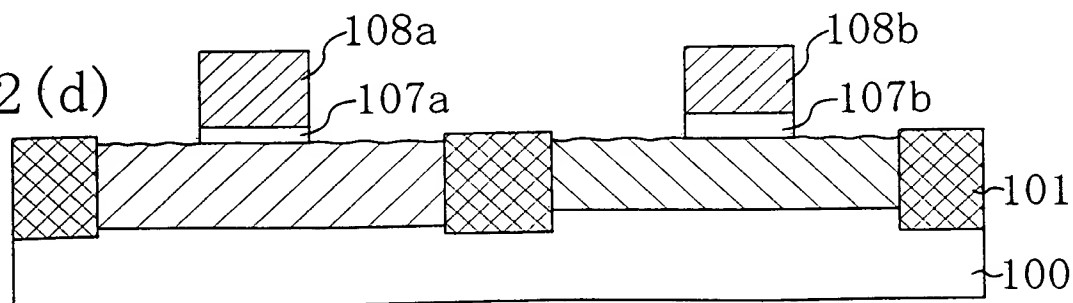


Fig. 22(d)



004760" 40029960

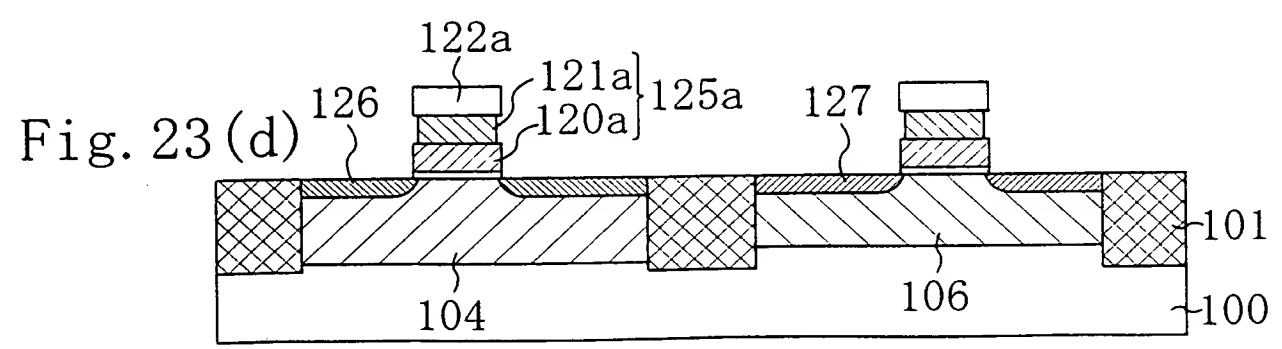
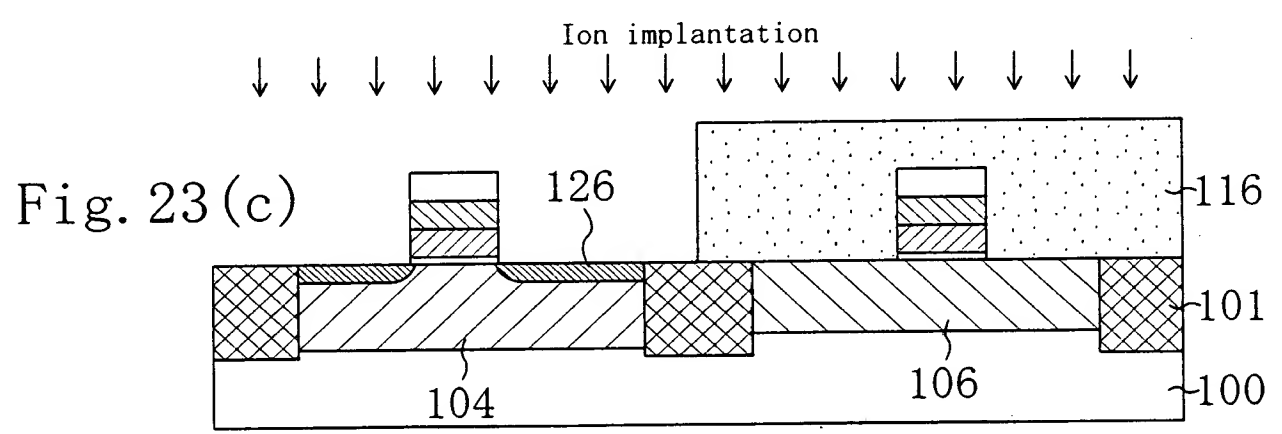
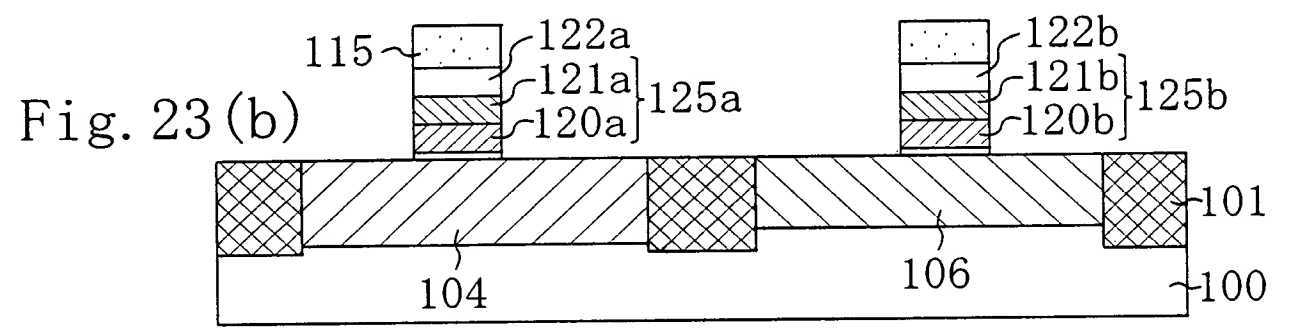
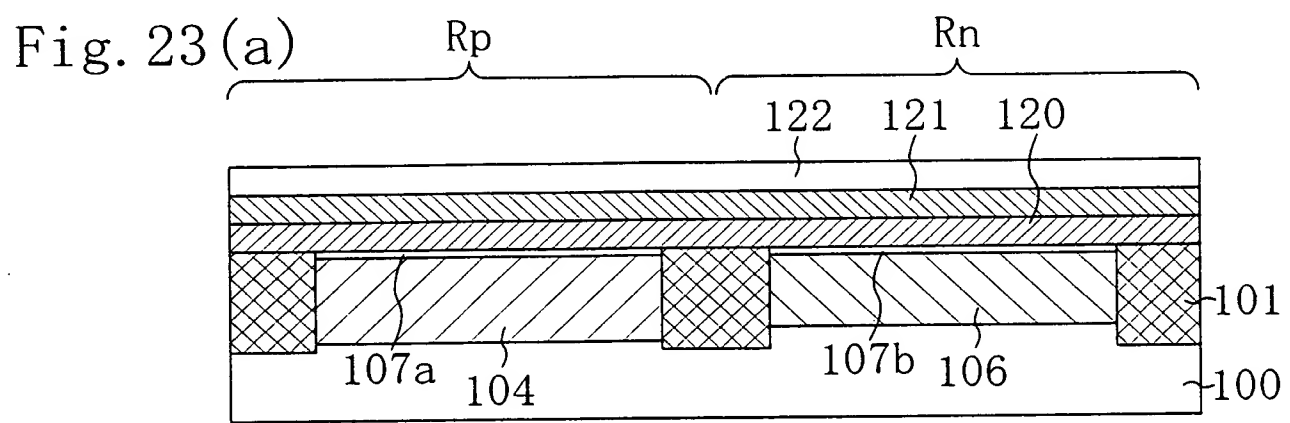


Fig. 24(a)

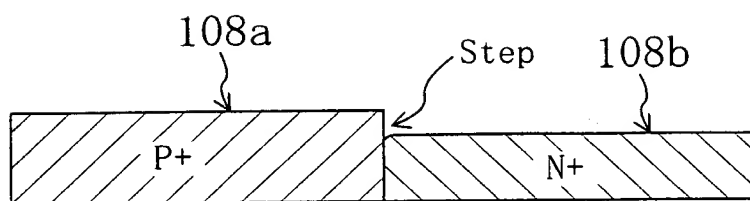


Fig. 24(b)

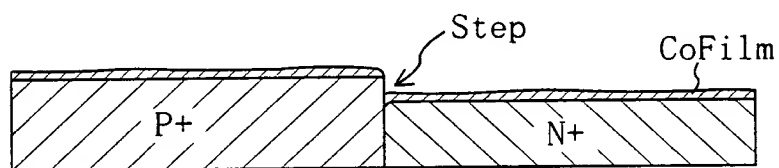


Fig. 24(c)

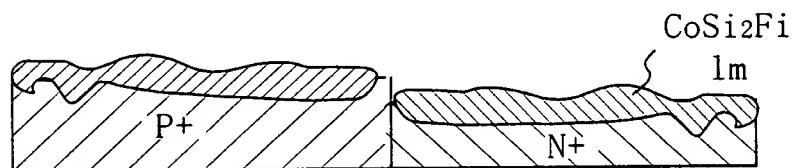


Fig. 25

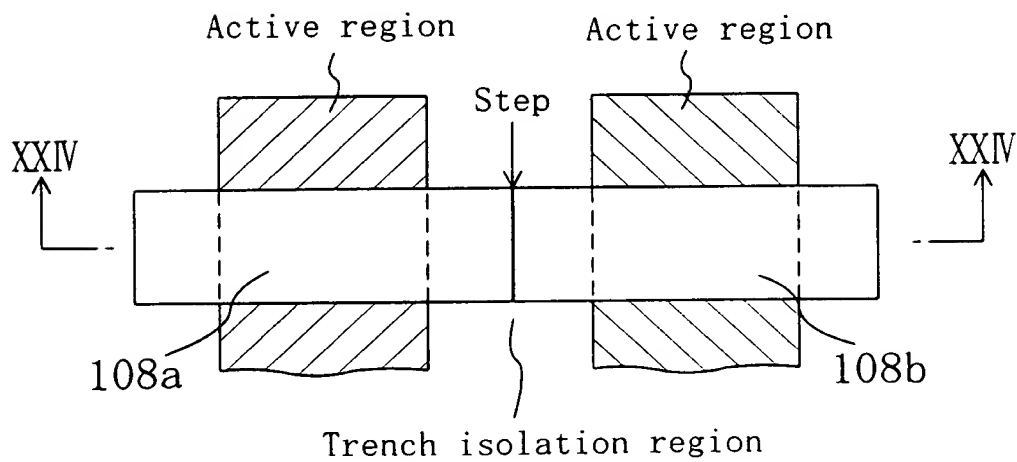
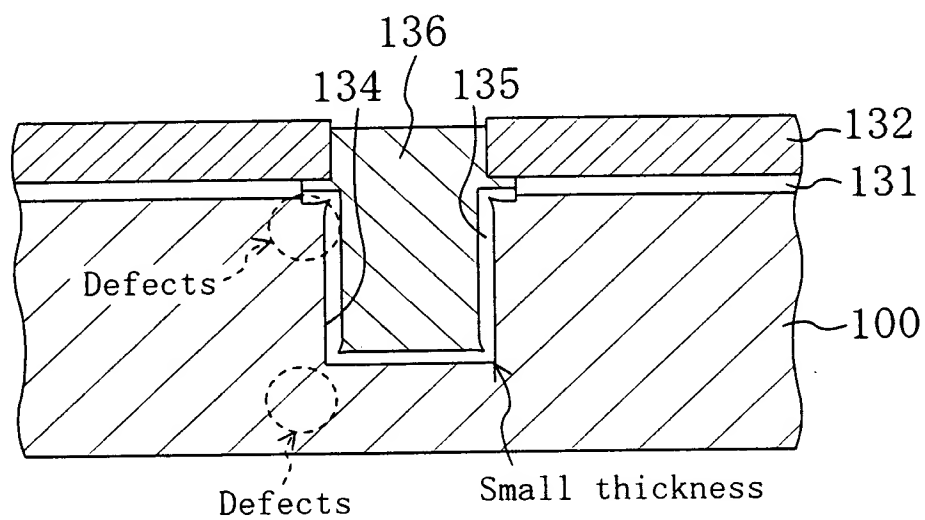


Fig. 26



004T50" 40029960